Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-13 (Withdrawn)

Claims 14-17 (Cancelled)

18. (Currently amended) A method <u>of manufacturing a heating element for a printhead, said method comprising</u> according to Claim 14, wherein forming a conductive layer comprises:

forming an insulating layer on <u>a</u> the substrate;

partially etching through the thickness removing portions of the insulating layer to define a protruding portion <u>having substantially vertical sidewalls and</u> flanked by two shoulder portions;

depositing forming a conductive layer on the insulating layer to cover the protruding portion and the shoulder portions; and

planarizing a surface of the conductive layer to expose the protruding portion to thereby <u>form a separate the</u> first conductive trace <u>separate</u> from <u>a</u> the second conductive trace; and

forming a resistive layer over the planarized surface of the conductive layer and the exposed protruding portion.

19. (Currently amended) A method according to Claim <u>18</u> 14, wherein the resistive layer is at least substantially uniformly thick.

20. (New) A method for manufacturing a thermal inkjet printhead, said method comprising:

forming an insulating layer on a substrate;

partially etching through the thickness of the insulating layer to define a protruding portion having substantially vertical sidewalls and flanked by two shoulder portions;

depositing a conductive layer on the insulating layer to cover the protruding portion and the shoulder portions;

planarizing a surface of the conductive layer to expose the protruding portion to thereby form a first conductive trace separate from a second conductive trace; and

forming a resistive layer over the planarized surface of the conductive layer and the exposed protruding portion; and

forming an ink chamber above the resistive layer.

21. (New) The method of claim 20 further comprising:

forming a passivation layer between the resistive layer and the ink chamber, said passivation layer being made of an insulating material.

22. (New) The method of claim 21 further comprising:

forming a cavitation barrier layer between the passivation layer and the ink chamber.